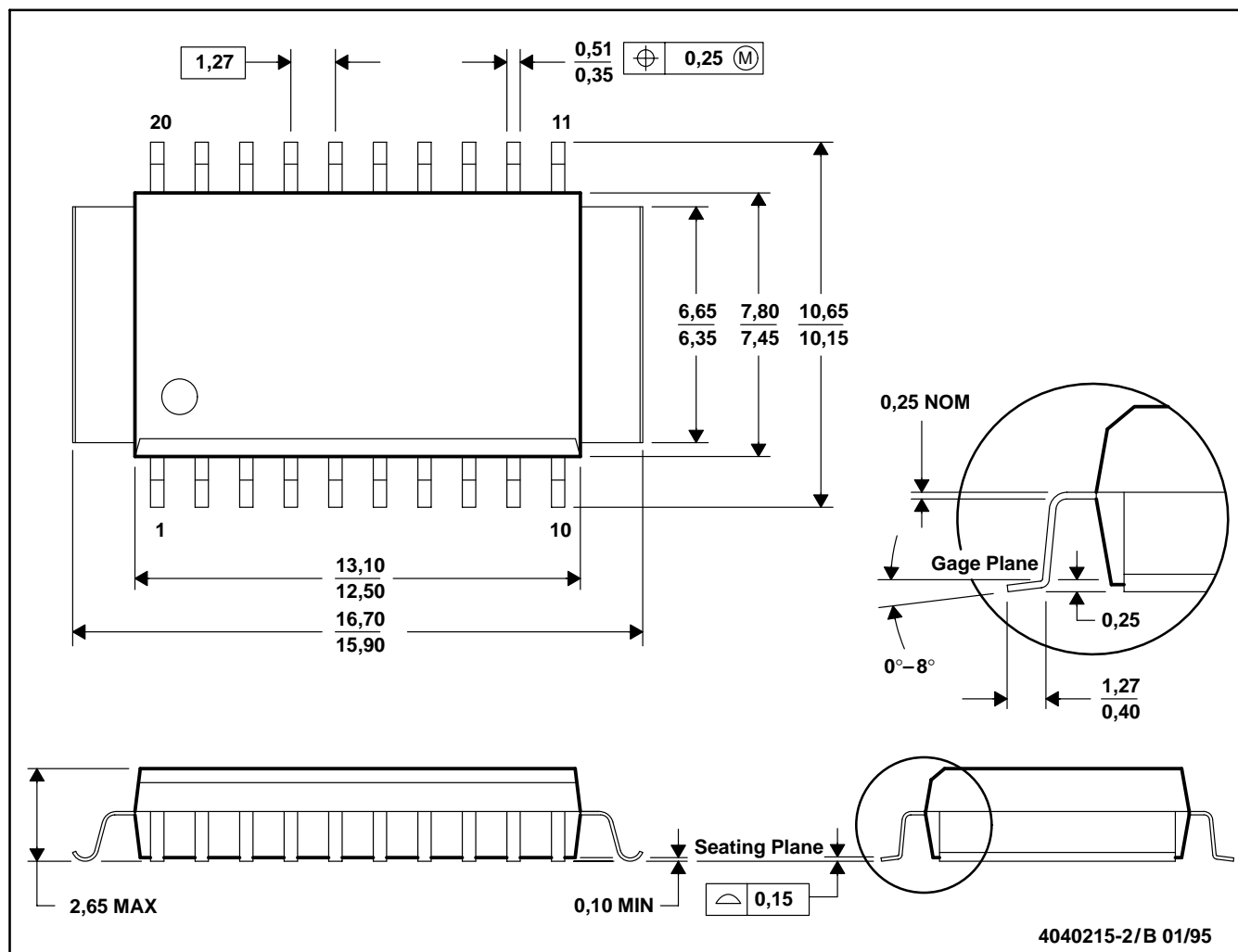


DSB (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion.
 D. Thermally enhanced molded plastic package with end tabs connected to die pad



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